

SPECIFICATION

产品规格书

NO.(编号) : NCYM-DS-0XX

Customer(客户) :

Part No.(型号) : 5050RGB05-06-UT16-F03

Description(描述) : 5050RGB

Model(说明) :

Version(版本) : R&D SPEC

CUSTOMER APPEROVED (客户审核)	APPROVED (核准)	ISSUED (制定)
	朱磊	杨攀

The RGB 5050 package has high efficiency intensity output, mid power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for a broad range of lighting applications
此款5050RGB 产品具有高效率，低功耗，发光角度广等一系列特性，这些特点使其成为广泛照明应用的理想LED。



FEATURES/特点

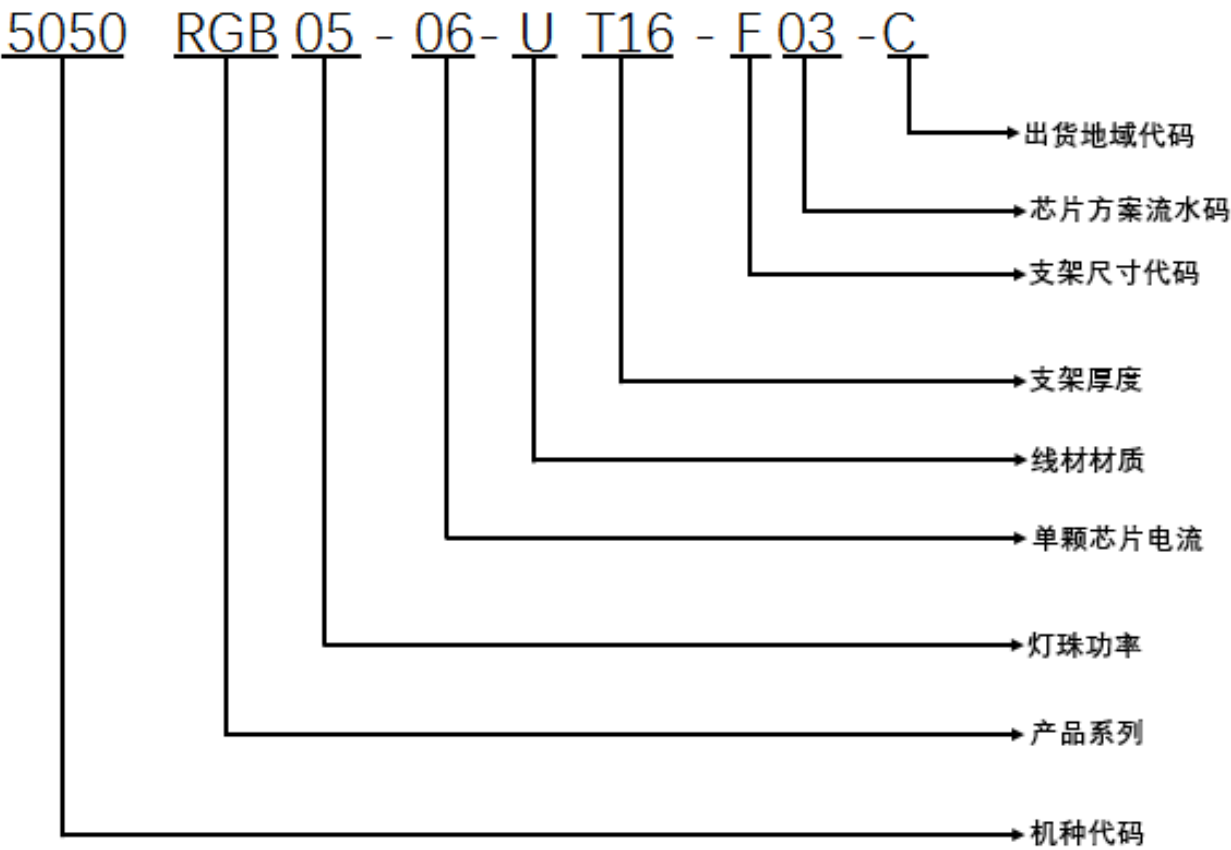
- High luminous Intensity and high efficiency
高亮度、高光效
- Compatible with reflow soldering process
匹配回流焊制程
- Low thermal resistance/热阻低
- Long operation life/寿命长
- Wide viewing angle at 120°
120° 大发光角度
- Silicone encapsulation/硅胶封装
- Environmental friendly, RoHS compliance
材质环保，符合RoHS要求
- Qualified according to JEDEC moisture sensitivity Level 4/符合JEDEC湿度敏感等级4

APPLICATIONS

- Indicators /指示灯
- Illumination /灯彩装饰
- Decorative and Entertainment Lighting /装饰和娱乐照明
- Decorative and landscape lighting
装饰和景观照明
- Signage and channel letter
标识和发光字
- Decorating and entertainment lighting
装修和娱乐照明
- Architectural lighting
建筑照明

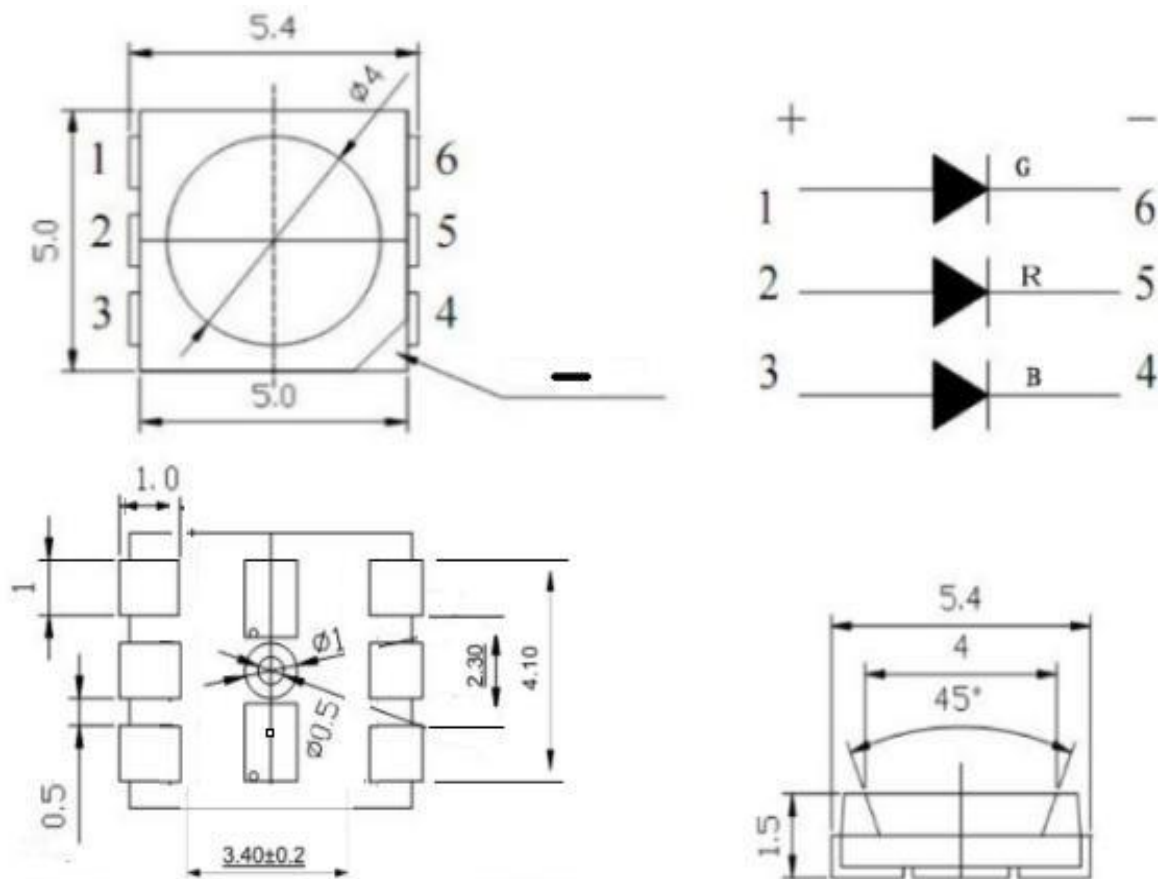
Note: The information in this document is subject to change without notice.
注:本文件内的资料如有更改，恕不另行通知。

PRODUCT NAMING SPECIFICATION 产品命名规范



机种代码 XXXX	5050 ; 3528 ; 5054 ; 3030 ; 2835 ;
产品系列 XXX	RGB ;
灯珠功率 XX	02:0.2W ; 05:0.5W ; 10:1.0W ; 15:1.5W ;
单颗芯片电流 XX	02:20mA ; 03:30mA ; 06:60mA ; 10:100mA ; 12:120mA ;
线材材质 X	U : 金线 ; K : K金线 ; G : 合金线 ;
支架厚度 XXX	T13:1.3mm ; T14:1.4mm ; T17:1.75mm ; T18:1.85mm ; T19:1.9mm ;
支架尺寸代码 X	R:2835 ; T:3030 ; F:5050 ;
芯片方案流水码 XX	代表芯片方案
出货地域代码 X	默认China ; J:Japan ; US:America

PACKAGE DIMENSIONS 封装尺寸



Notes/ 注:

1. All dimensions in millimeters. 所有尺寸单位为 mm
2. Thickness tolerance of copper plate is ± 0.02 mm. 铜材料片厚度公差为 ± 0.02 mm
3. Thickness tolerance of product is ± 0.05 mm. 产品厚度公差为 ± 0.02 mm
4. Tolerance is ± 0.1 mm unless otherwise noted. 如未特别注明，默认公差为 ± 0.1 mm

ABSOLUTE MAXIMUM RATINGS 最大限定参数 (Ta=25℃)

Parameter 项目名称	Symbol 符号	Absolute Maximum Rating 绝对最大额定值			Unit 单位
		Red 红光	Green 绿光	Blue 蓝光	
Forward current 正向电流	IF	70	70	70	mA
Peak Forward Current 正向脉冲电流	IFP	60	60	60	mA
Power Dissipation 消耗功率	Pd	132	204	188	mW
Operating Temperature 工作温度	Topr	-30~+80			℃
Storage Temperature 储存温度	Tstg	-40~+85			℃
Soldering Temperature 焊接温度	Tsld	Reflow Soldering: 260℃ for 10 seconds 回流焊 : 260℃ 10s			
LED Junction Temperature 结温	Tj	110			℃

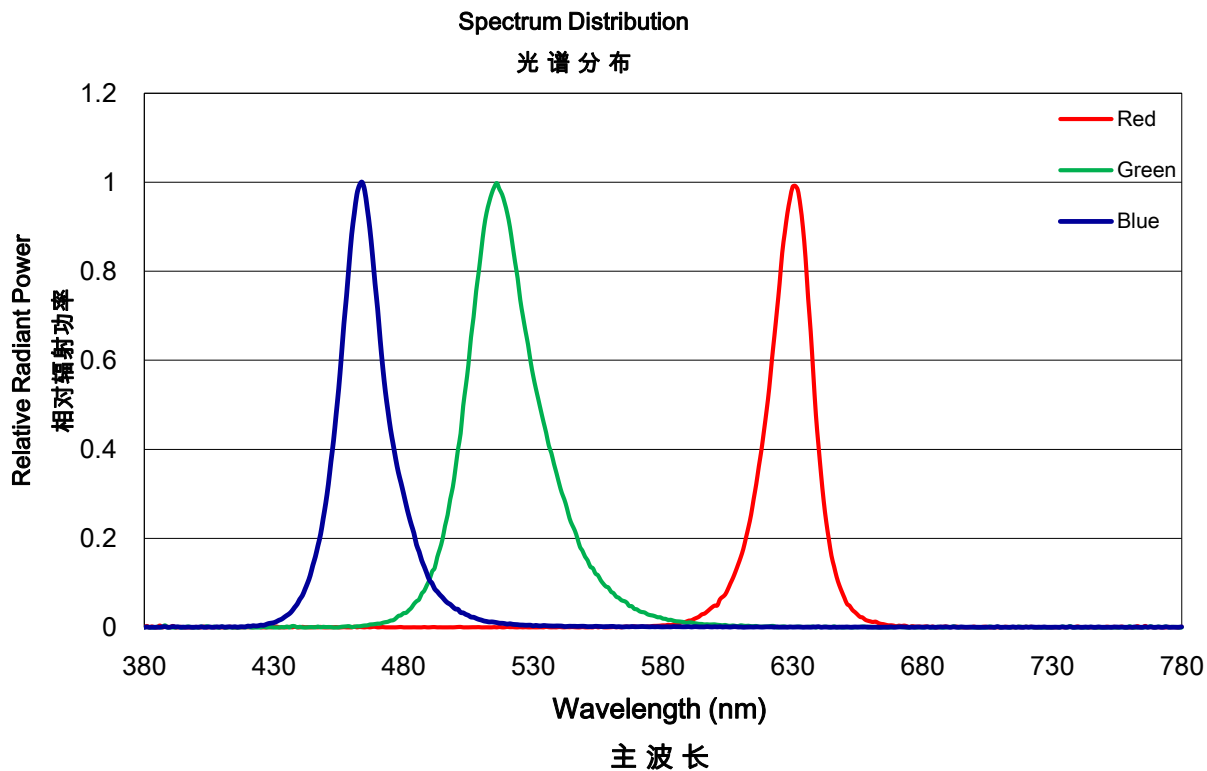
ELECTRO-OPTICAL CHARACTERISTICS 主要光电参数(Ta=25℃)

Parameter 参数	Symbol 符号	Color 颜色	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Coondition 条件
Forward Voltage 正向电压	VF	Red 红光	1.9	---	2.3	V	IF=60mA
		Green 绿光	3.2	---	3.5	V	
		Blue 蓝光	2.9	---	3.2	V	
Luminous Flux 光通量	Φ	Red 红光	9.0	---	12.0	lm	
		Green 绿光	18.0	---	22.0		
		Blue 蓝光	3.0	---	5.0		
Dominate Wavelength 主波长	WD	Red 红光	615	---	625	nm	
		Green 绿光	515	---	525		
		Blue 蓝光	460	---	470		
Reverse Current 反向电流	Ir	Red 红光	0	---	1.0	uA	Vr=-10V
		Green 绿光	0	---	1.0	uA	Vr=-10V
		Blue 蓝光	0	---	1.0	uA	Vr=-13V

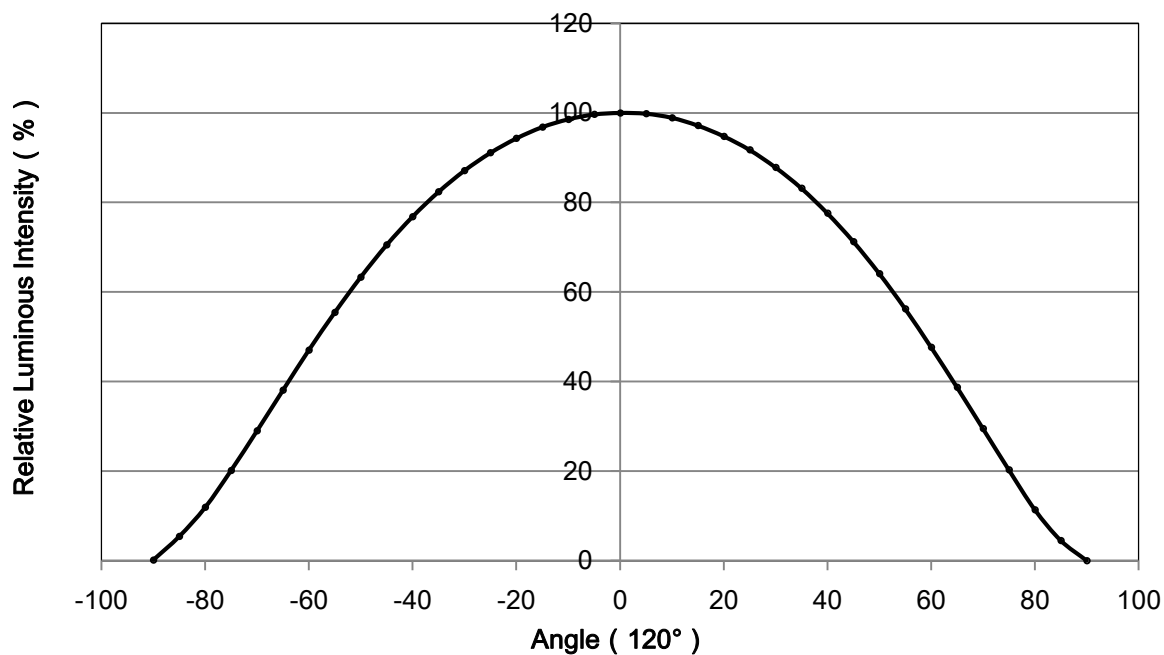
Notes 注:

- Luminous flux is measured with an accuracy of $\pm 5\%$. 光通量的测量精度为 $\pm 5\%$.
- Chromaticity coordinate bins are measured with an accuracy of ± 0.01 . 色度坐标相对测量精度为 ± 0.01
- All measurements were made under the standardized environment of Shineon
所有的测量都是在易美的标准环境下进行的

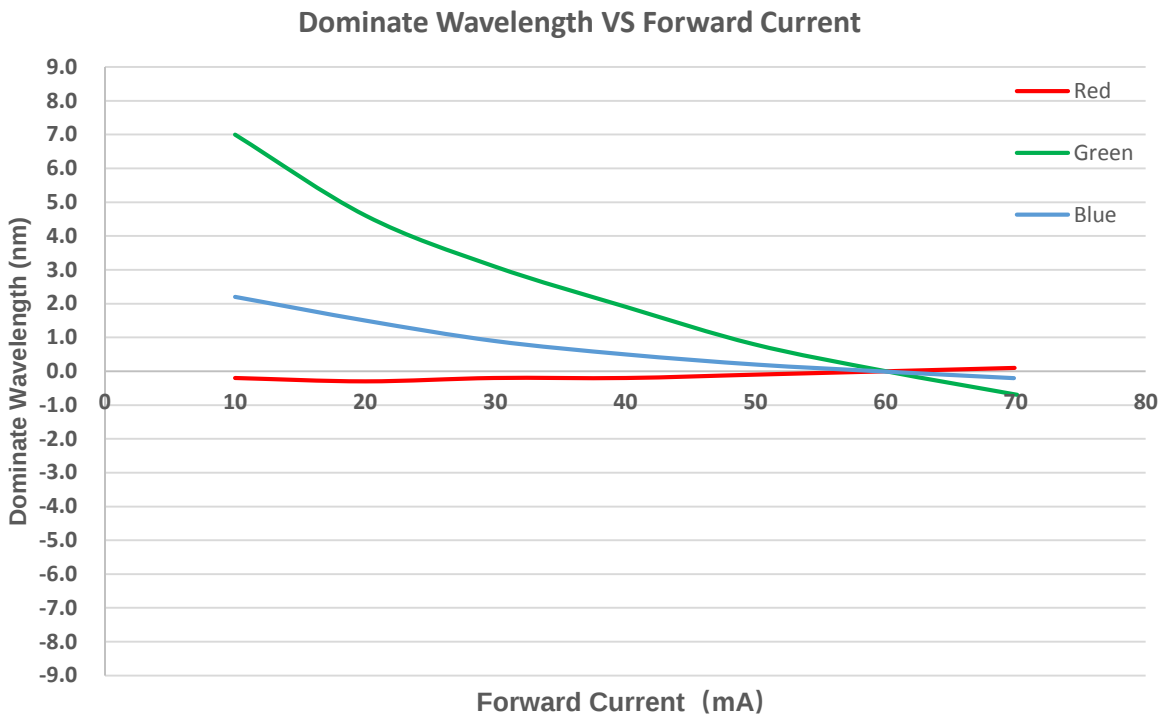
RELATIVE SPECTRAL POWER DISTRIBUTION 相对光谱功率分布 ($T_j=25^{\circ}\text{C}$)



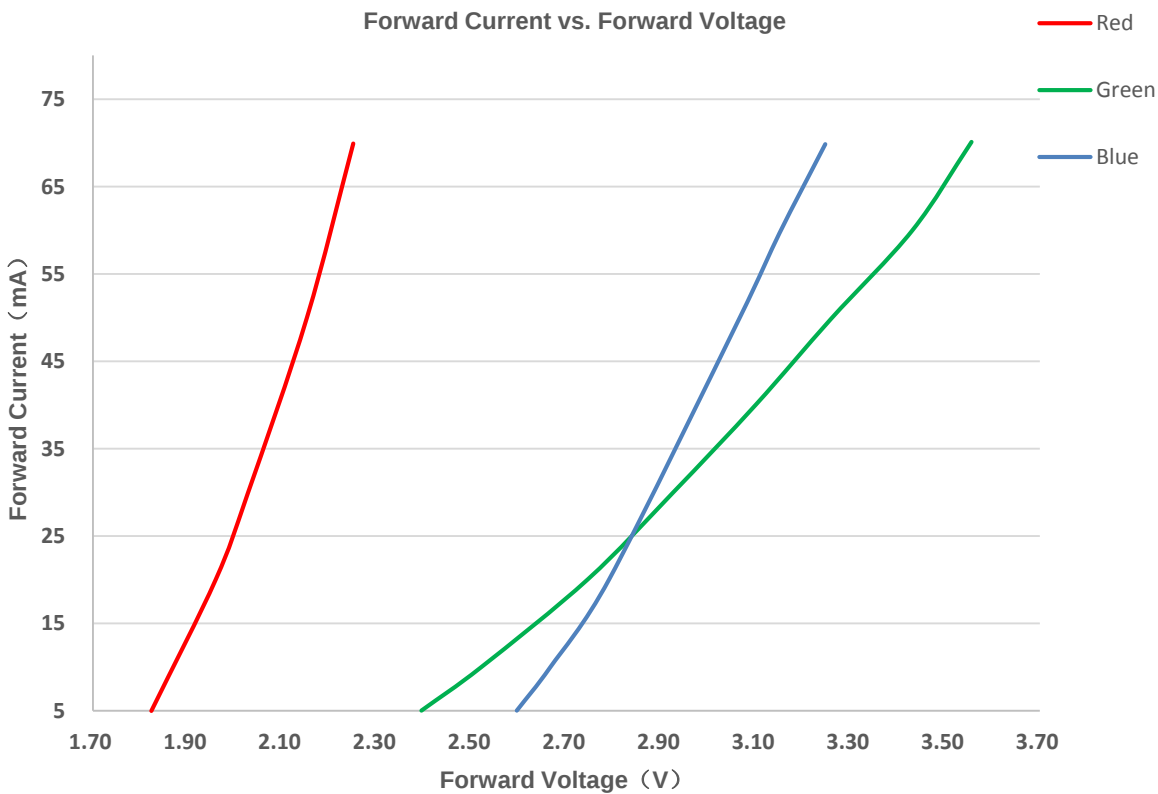
TYPICAL SPATIAL DISTRIBUTION 典型配光分布



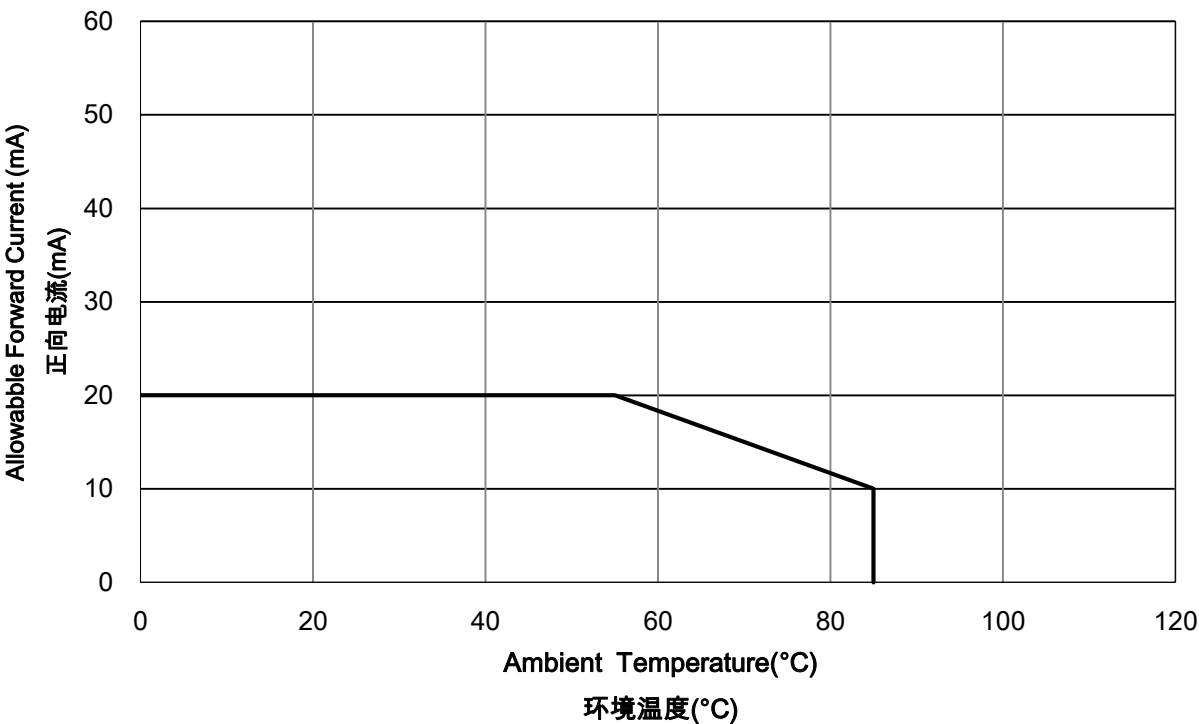
RELATIVE LUMINOUS FLUX VS. CURRENT ($T_j=25^{\circ}\text{C}$)



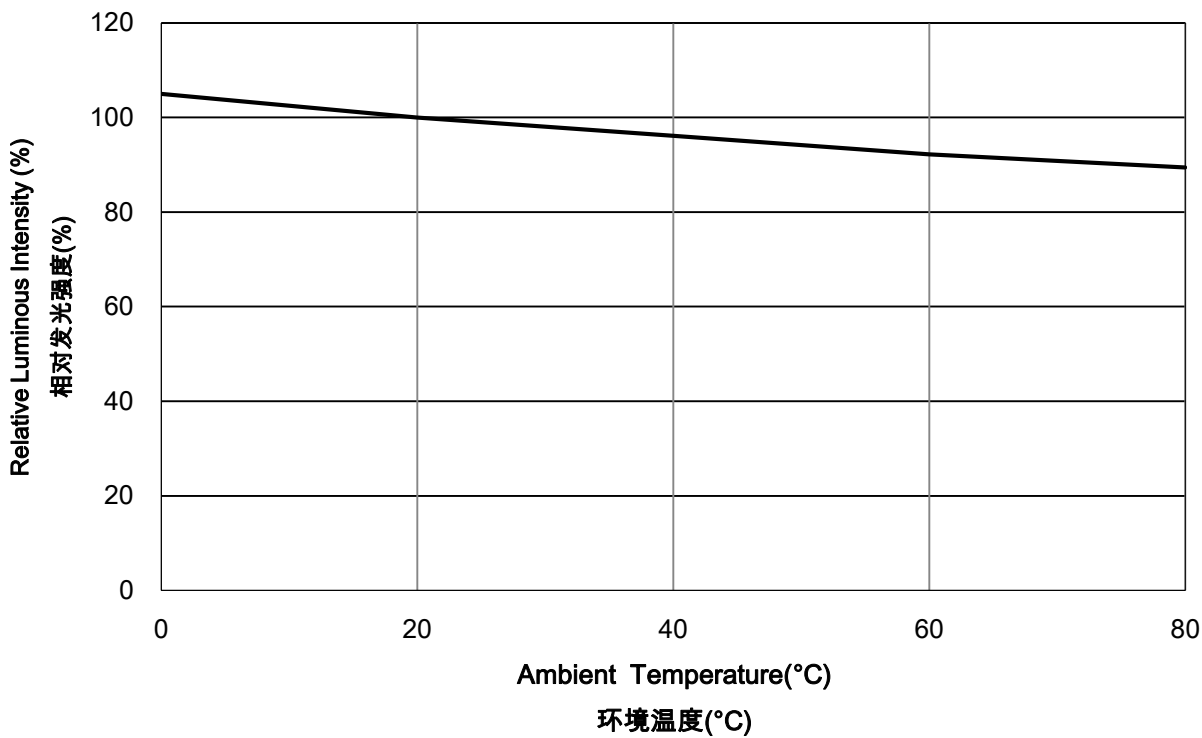
ELECTRICAL CHARACTERISTICS ($T_j=25^{\circ}\text{C}$)



MAXIUM CURRENT VS. AMBIENT TEMPERATURE



RELATIVE RADIANT FLUX VS. JUNCTION TEMPERATURE



SORTING RANKS 分光等级

(1) Bin Range of Luminous Intensity / 光强及光通量 (Tj=25°C)

luminous flux (lm) 光通量(流明)								
Red 红光			Green 绿光			Blue 蓝光		
Bin Code	Min 最小值	Max 最大值	Bin Code	Min 最小值	Max 最大值	Bin Code	Min 最小值	Max 最大值
MA	10.0	12.0	ME	18.0	20.0	EI	3.0	5.0

(2) Bin range of Dominate Wavelength 主波长划分(Tj=25°C)

Dominate Wavelength 主波长划分								
Red(nm)红光(波长)			Green(nm) 绿光(波长)			Blue(nm)蓝光(波长)		
Bin Code	Min 最小值	Max 最大值	Bin Code	Min 最小值	Max 最大值	Bin Code	Min 最小值	Max 最大值
R617	617.5	620.0	G520	520.0	522.5	B465	465.0	467.5
R620	620.0	622.5	G522	522.5	525.0	B467	467.5	470.0

(3) Bin range of Forward Voltage 电压Bin

Color 颜色	Bin Code 代码	Min 最小值	Max 最大值	Color 颜色	Bin Code 代码	Min 最小值	Max 最大值	Color 颜色	Bin Code 代码	Min 最小值	Max 最大值
Red 红光	A3	2.10	2.20	Green 绿光	B4	3.40	3.50	Blue 蓝光	B0	3.00	3.10
	A4	2.20	2.30		B5	3.50	3.60		B1	3.10	3.20

Notes 注：

1. 5% tolerance for luminous intensity may be caused by measurement inaccuracy.
光通量测量精度误差± 5%
2. Measurement Uncertainty of the Forward Voltage : ± 3%
正向电压测量误差:± 3%

REFLOW SOLDERING CHARACTERISTICS 回流焊特性

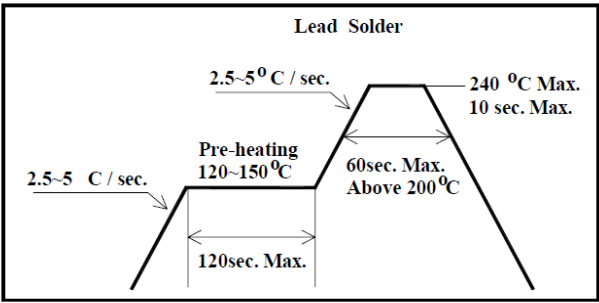
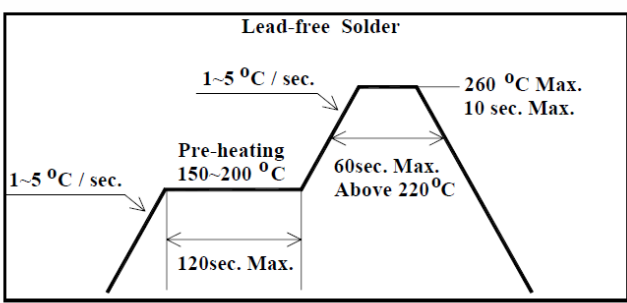
For Reflow Process 回流焊制程:

Preheating 预热 : 140℃~160℃±5℃, within 2 minutes. 2分钟

Operation heating 作业加热 : 260℃(Max.) within 10 seconds.(Max)

260℃(最高) within 10 seconds.(最长)

Gradual Cooling (Avoid quenching). 逐渐冷却(避免淬火)

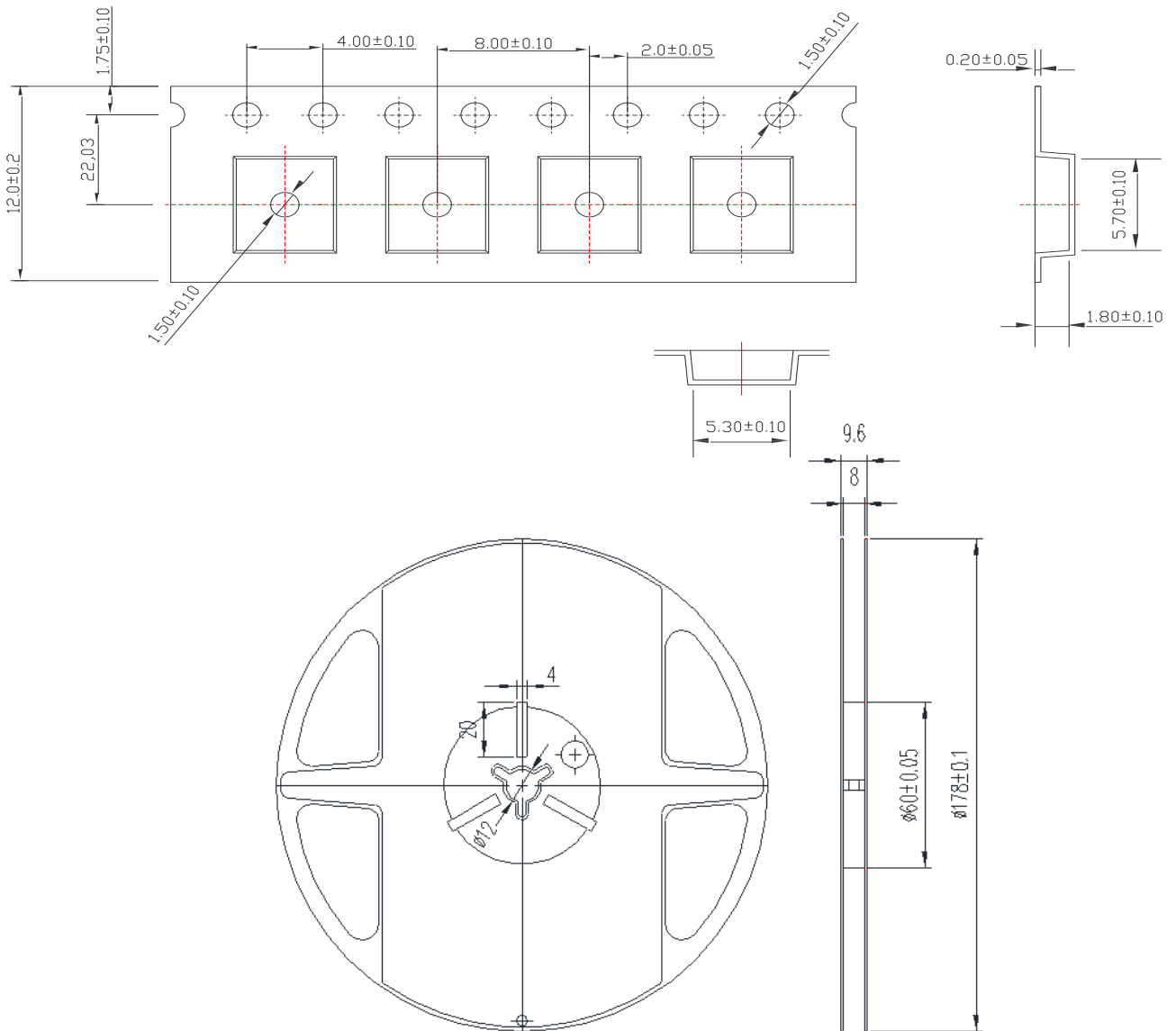
Lead solder 有铅焊接		Lead-free solder 无铅焊接	
Pre-heat 预热	120-150℃	Pre-heat 预热	150-200℃
Pre-heat time 预热实际那	120 sec.Max.	Pre-heat time 预热实际那	120 sec.Max.
Peak Temperature 峰值温度	240℃ Max.	Peak Temperature 峰值温度	260℃ Max.
Soldering time condition 回流焊时间	10 sec.Max.	Soldering time condition 回流焊时间	10 sec.Max.
			

Notes 注:

The encapsulated material of the LEDs is silicone . Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.

由于LED的封装材料是硅胶，led封装顶部表面是柔软的，顶部表面的压力会影响led的可靠性。应采取预防措施，以避免密封部件受到强大的压力。因此，在使用吸嘴时，应使硅胶表面的压力适中。

TAPE AND REEL 编带

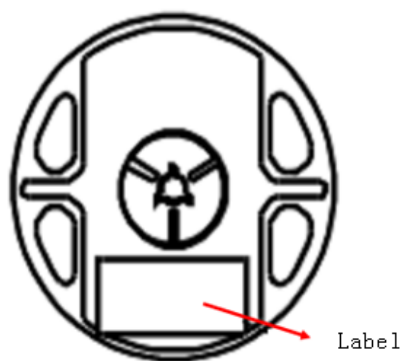
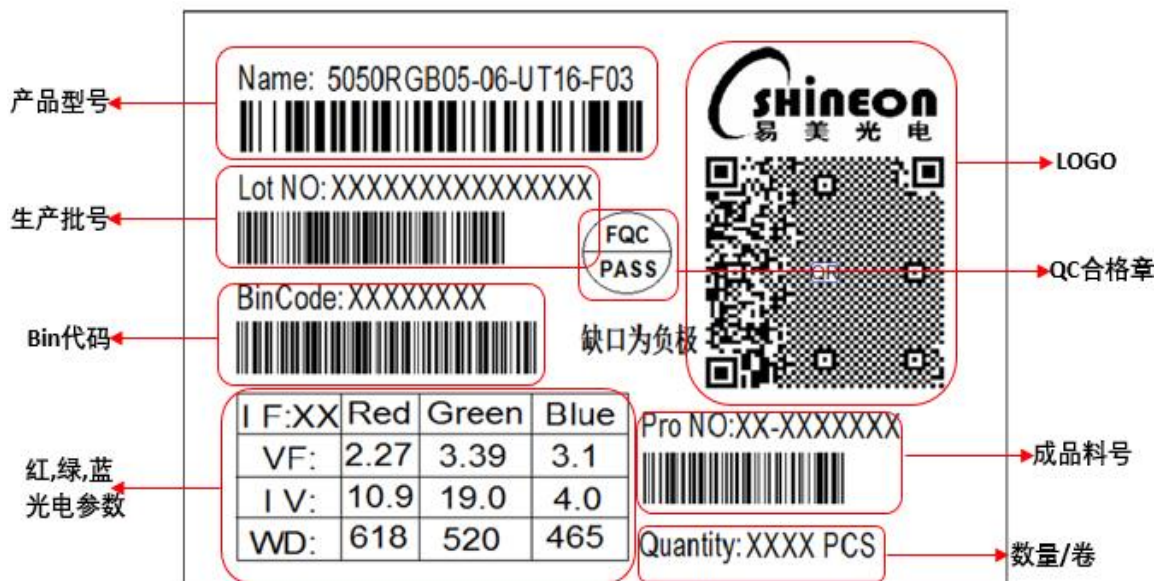


Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit=mm

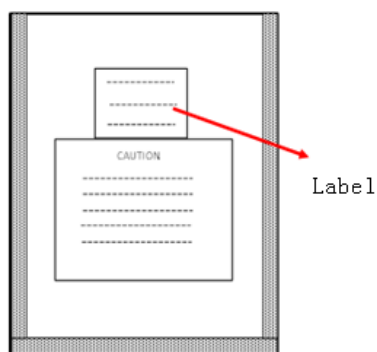
Notes注:

- (1) Quantity : 2500pcs/Reel
数量 : 2500pcs/卷
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be $\pm 0.2\text{mm}$
累积公差: 累积公差/10间距 $\pm 0.2\text{毫米}$
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape
盖带粘附强度: 盖带反向拉, 与载带角度为 10° , 拉力为 0.1-0.7N
- (4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package.
包装 : 品名, 生产数据代码和数量须在防潮包装上注明

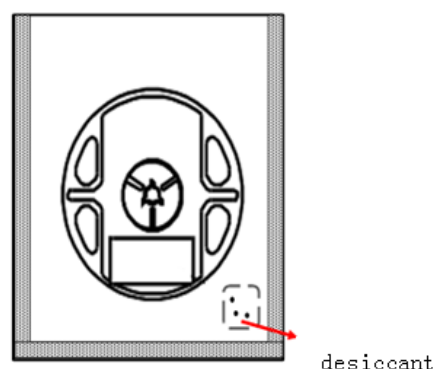
PACKAGING 包装



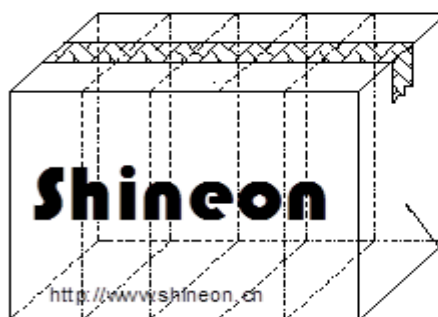
REEL
卷盘



moisture-proof bag
防潮袋



干燥包



Outside box
Maximums 48 Reels

外箱
最多48卷盘

Reliability Test Items 可靠性测试项目

Test Items 测试项目	Test Duration 测试时长	Number of Damaged 不良数
Steady State Operating Life of High Temperature (HTOL) $T_s=85^{\circ}\text{C}$, $I_F=\text{Max}$ 高温点亮稳态老化 $T_s=85^{\circ}\text{C}$, $I_F=\text{最大值}$	1000hrs	0/20
Steady State Operating Life of Low Temperature (LTOL) $T_a=-40^{\circ}\text{C}$, $I_F=\text{Max}$ 低温点亮稳态老化 $T_s=85^{\circ}\text{C}$, $I_F=\text{最大值}$	1000hrs	0/20
Pulse Wet Operating Life of High Temperature (PWHTOL) 高温高湿通断电老化 $85^{\circ}\text{C}85\%\text{RH}$, $I_F30\text{mins ON}/30\text{min OFF}$	500hrs	0/20
High Temperature Storage (HTS) 高温存储 100°C	1000hrs	0/20
Low Temperature Storage (LTS) 低温存储 -40°C	1000hrs	0/20
Thermal Shock (TS) $-45^{\circ}\text{C}\sim 125^{\circ}\text{C}$ 15min dwell 20sec transfer 冷热冲击 -45°C 15min $\sim 125^{\circ}\text{C}$ 15min, 转换时间20秒	300cycles	0/20
Solder Resistance (SR) 265°C , 3X MSL 阻焊测试 (3遍潮气敏感度试验后)	5sec	0/20
Solder Ability (SA) $245^{\circ}\text{C}5\text{sec}$, 95% coverage 可焊性 95%覆盖	5sec	0/11
Mechanical Shock (MS) 1500G 0.5msec pulse shock 机械冲击(MS) 1500G 0.5毫秒脉冲冲击	Each6 axis	0/6
Random Vibration (RV) 随机振动 6G RMS, 10-2000Hz, 10min	Per axis	0/6
Variable Vibration Frequency (VVF) 10-2000-10Hz, log or linear sweep rate, 20G for 1 min, 1.5mm each apply 3x per axis over 变频振动(VVF) 10-2000-10Hz, 对数或线性扫频, 20G, 1分钟, 1.5mm, 每轴3遍以上	6hrs	0/6
Salt Spread (SS) 35°C , 30g/m ² /day 盐雾试验 35°C ,30克/平方米/天	48hrs	0/11

Item 项目	Symbol 符号	Test Condition 测试条件	Criteria for Judgment 判定标准	
			Min. 最小	Max. 最大
Forward Voltage 正向电压	V_f	$I_F=\text{Typical Current}$ 典型电流		U.S.L x1.1
Luminous Flux 光通量	I_m	$I_F=\text{Typical Current}$ 典型电流	L.S.L x0.7	
CCX&CCY X坐标&Y坐标	x,y	$I_F=\text{Typical Current}$ 典型电流		Shift<0.02 漂移<0.02

PRECAUTION FOR USE 使用注意事项

(1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA should be used.

本器件不得用于水、油、有机溶剂等任何流体中。如需清洁，请使用异丙醇进行清洗。

(2) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.

当LED发光工作时，应根据环境最高温度来确定工作电流。

(3) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3months or more after being shipped from ShineOn, a sealed container with a nitrogen atmosphere should be used for storage.

LED储存环境须保持清洁。如果LED从易美发货后需储存3个月或更长时间，则应使用氮气柜进行储存。

(4) The LEDs must be used within 72 Hours after opening the moisture proof packing. Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.

LED须在打开防潮包装后72小时内使用。用防潮包装重新包装未使用的产品，折叠以封住开口，然后存放在干燥的地方。

(5) The appearance and specifications of the product may be modified for improvement without notice.

产品外观及规格如有改进，恕不另行通知。

(6) This LED is sensitive to the static electricity and surge. It is recommended to use a wrist Band or anti-electrostatic glove when handling the LEDs.

LED对静电和浪涌很敏感。在处理LED时，建议使用防静电腕带或防静电手套。

(7) On manual soldering, a solder tip must be needed as grounded for usage. If over voltage which exceeds the absolute maximum rating is applied to LEDs, it will cause damage LEDs and result in destruction. Damaged LEDs will show some unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LEDs get unlighted at low current.

手工焊接时，焊接头必须接地。如果对led施加超过绝对最大额定值的过电压，会对led造成损坏。损坏的led会出现一些不寻常的特性，如漏电流明显增加，接通电压降低，低电流时led不亮。